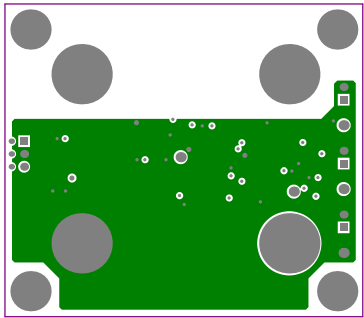
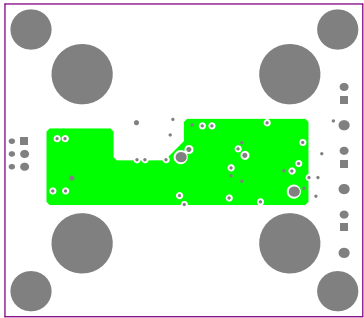


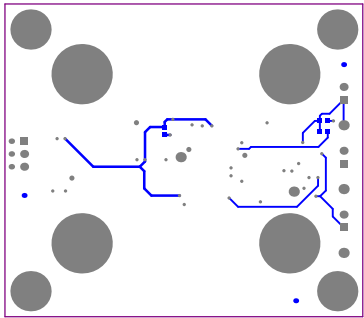
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 6/8/2015	6:10:12 PM	TEXAS INSTRUMENTS



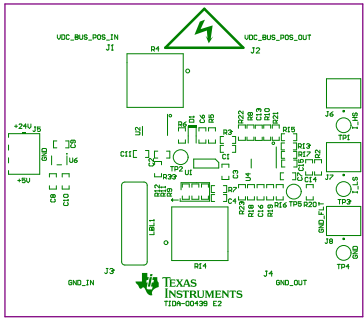
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = GND	TID #:		
PLOT NAME = GND	GENERATED : 6/8/2015	6:10:12 PM	TEXAS INSTRUMENTS



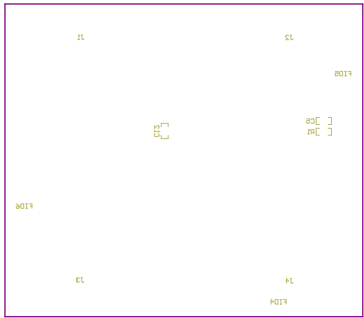
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = POWER	TID #:		
PLOT NAME = POWER	GENERATED : 6/8/2015	6:10:12 PM	TEXAS INSTRUMENTS



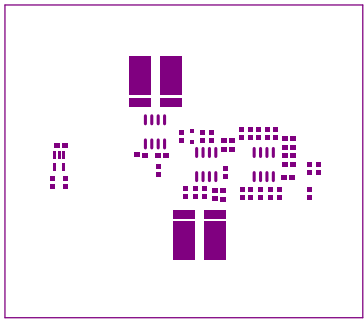
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 6/8/2015	6:10:12 PM	TEXAS INSTRUMENTS



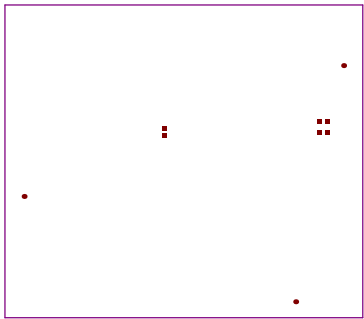
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Silkscreen Overlay	GENERATED : 6/8/2015	6:10:12 PM	TEXAS INSTRUMENTS



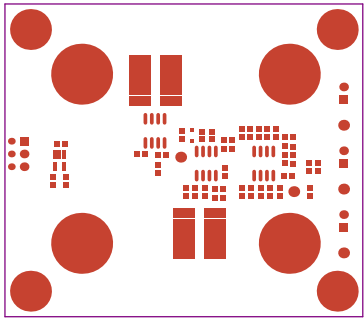
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 6/8/2015	6:10:12 PM	TEXAS INSTRUMENTS



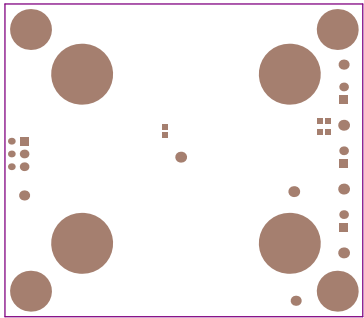
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #:		
PLOT NAME = Top Paste Mask Print	GENERATED : 6/8/2015 6:10:12 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #:		
PLOT NAME = Bottom Paste Mask Print	GENERATED : 6/8/2015 6:10:12 PM	TEXAS INSTRUMENTS	

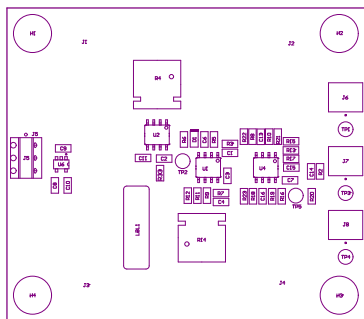


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask Print	GENERATED : 6/8/2015 6:10:12 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask Print	GENERATED : 6/8/2015 6:10:12 PM	TEXAS INSTRUMENTS	

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

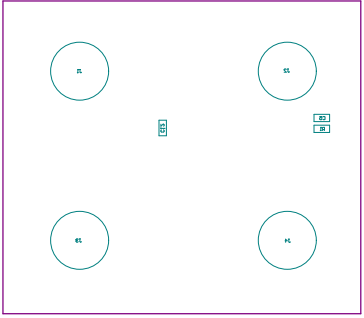


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SUN REV: Not In VersionControl
M5 Assembly Top	TID #:		
PLOT NAME = M5 Assembly Top	GENERATED : 6/8/2015	6:10:13 PM	TEXAS INSTRUMENTS

PCB VIEWED FROM BOTTOM SIDE	BOARD # : TIDA-00439	REV: E3	SVN REV: Not In VersionControl
	TID # :	M6 Assembly Bottom	
PLOT NAME = M6 Assembly Bottom	GENERATED : 6/8/2018 10:13 PM	TEXTS INSTRUMENTS	

COMPONENTS MARKED 'DNP', SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT 001



Layer Stack Up Detail for: TIDA-00439-E2.PcbDoc			
Layer Name	Color	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
TOP LAYER	(.GTL)	1.4mil	FR-408
I.2-DR-PLANE	(.GDI)	1.4mil	FR-408
I.2-POSR-PLANE	(.GSD)	1.4mil	FR-408
BOTTOM LAYER	(.GBL)	1.4mil	FR-408
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2800.00 MIL X 2450.00MIL

MIN. TRACK WIDTH: 15 MIL
 MIN. CLEARANCE: 10 MIL
 MIN. VIA PAD SIZE: 26 MIL

MINIMUM ANNULAR RING 0.1778mm (7MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- .5 MIL HOLES +/- .3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

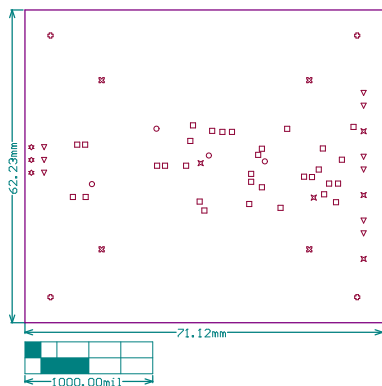
BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 MM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER _____ PER ORDER

ADDITIONAL REQUIREMENTS: U/A TENTING: YES NO
 MICROSECTION: YES IMPEDANCE CONTROL: YES NO
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SILK



Drill Table

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	32	12mil (0.305mm)	PTH	Round
○	4	20mil (0.508mm)	PTH	Round
×	5	40mil (1.016mm)	PTH	Round
*	3	43.307mil (1.1mm)	NPTH	Round
▽	9	43.307mil (1.1mm)	PTH	Round
⊙	4	125.984mil (3.2mm)	PTH	Round
⊞	4	270mil (6.858mm)	PTH	Round
	61 Total			

DRILL TOLERANCE
 FOR PTH +/- 3MIL
 FOR NPTH +/- 2MIL
 12mil drill: +0/-12mil



PROJECT TITLE:
270U Earth Leakage Protection

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00439.PcbDoc

ENGINEER: Pavan N

LAYOUT BY: Manjunath M

SCALE: 1:00

ALTIM DESIGNER VERSION: 10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00439	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing For (Bottom Layer) (TEBayer): 6/8/2015 6:10:13 PM	TEXAS INSTRUMENTS		

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